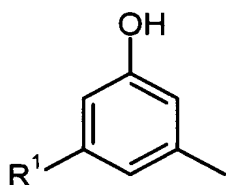


**Amendments to the Claims:**

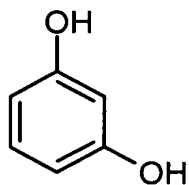
The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A two-component epoxy resin composition, ~~characterized in that~~wherein it comprises in the hardener component at least one Mannich base and after curing at a temperature between 5°C and 60°C has a glass transition temperature of more than 80°C.

2. (Currently Amended) The two-component epoxy resin composition as claimed in claim 1, ~~characterized in that~~wherein the Mannich base is prepared using a phenolic compound of the formula (I) or (II)



(I)



(II)

with  $R^1 = H$  or  $CH_3$ ,

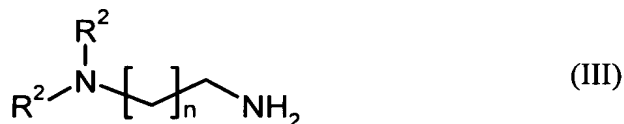
and also formaldehyde and at least one polyamine.

3. (Currently Amended) The two-component epoxy resin composition as claimed in claim 1, ~~characterized in that~~wherein the Mannich base is prepared using a phenolic compound of the formula (I) with  $R^1 = H$ .

4. (Currently Amended) The two-component epoxy resin composition as claimed in claim 1, ~~characterized in that~~wherein, for the preparation of the Mannich base, in a first stage at least one phenolic compound of the formula (I) or (II) is reacted with

formaldehyde in the presence of a tertiary amine and in a subsequent stage reaction takes place with at least one polyamine.

5. (Currently Amended) The two-component epoxy resin composition as claimed in claim 4, ~~characterized in that~~ wherein the tertiary amine has the formula (III)



with  $\text{R}^2 = \text{C}_1\text{-C}_6$  alkyl and  $n = 1, 2, \text{ or } 3$ .

6. (Currently Amended) The two-component epoxy resin composition as claimed in claim 1, ~~characterized in that~~ wherein the Mannich base contains not only secondary but also primary amino groups.

7. (Currently Amended) The two-component epoxy resin composition as claimed in ~~claim 1, characterized in that~~ claim 2, wherein the ~~polyamines~~ polyamine is selected from the group consisting of ~~encompassing~~ DAMP, 1,3-diaminopentane, IPDA, isophoronediamine, 1,3- and 1,4-diaminocyclohexane, 1,2-diaminocyclohexane 1,3- and 1,4-butanediamine, 1,3- and 1,5-pentanediamine, MPMD, 1,5-diamino-2-methylpentane, 1,3-xylylenediamine, 1,3-bis(aminomethyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diaza-octamethylenediamine), tetraethylenepentamine, pentamethylenehexamine, dipropylenetriamine, tripropylenetetramine, tetrapropylenepentamine, 4,7-diaza-decamethylene-1,10-diamine, bis(4-aminocyclohexyl)methane, bis(4-amino-3-methylcyclohexyl)methane, 3(4),8(9)bis(aminomethyl)tricyclo[5.2.1.0<sup>2,6</sup>]decane, and mixtures thereof.

8. (Currently Amended) The two-component epoxy resin composition as claimed in ~~claim 1, characterized in that~~ claim 2, wherein the polyamine is selected from the group consisting of ~~encompassing~~ 1,3-xylylenediamine, 1,3-bis(aminomethyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diazaoctamethylenediamine), tetraethylene-

pentamine, ~~IPDA~~, isophoronediamine, 1,2-diaminocyclohexane, 4,7-diaza-decamethylene-1,10-diamine, and mixtures thereof.

9. (Currently Amended) The two-component epoxy resin composition as claimed in claim 1, ~~characterized in that~~wherein curing takes place at a temperature between 10°C and 50°C, in particular between 10°C and 30°C.

10. (Currently Amended) The two-component epoxy resin composition as claimed in claim 1, ~~characterized in that~~wherein, after curing, the glass transition temperature is above 100°C, in particular between 100°C and 150°C.

11. (Currently Amended) The ~~use of a~~ two-component epoxy resin composition as claimed in claim ~~1 as an adhesive~~, 1, wherein the two-component epoxy resin composition is an adhesive.

12. (Currently Amended) The ~~use of a~~ two-component epoxy resin composition as claimed in claim 11, ~~characterized in that~~wherein the adhesive ~~is used for structural reinforcement~~reinforces a structure.

13. (Currently Amended) The ~~use of a~~ two-component epoxy resin composition as claimed in claim 12, ~~characterized in that~~wherein the adhesive ~~is used for bonding~~bonds fiber-reinforced composites to built structures.

14. (Currently Amended) The ~~use of a~~ two-component epoxy resin composition as claimed in claim ~~1 as~~1, wherein the two-component epoxy resin composition is a polymeric matrix for producing fiber-reinforced composites.

15. (Currently Amended) A fiber-reinforced composite, ~~characterized in that~~wherein it is produced using a two-component epoxy resin composition as claimed in claim 1.

16. (Currently Amended) A method of adhesive bonding, ~~characterized in that~~wherein a two-component epoxy resin composition as claimed in claim 1 is mounted to at least one solid's surface and subsequently contacted with at least one further solid's surface.

17. (Previously Presented) A cured product obtained from a two-component epoxy resin composition as claimed in claim 1.

18. (New) The two-component epoxy resin composition as claimed in claim 4, wherein the polyamine is selected from the group consisting of 1,3-diaminopentane, isophoronediamine, 1,3- and 1,4-diaminocyclohexane, 1,2-diaminocyclohexane 1,3- and 1,4-butanediamine, 1,3- and 1,5-pentanediamine, 1,5-diamino-2-methylpentane, 1,3-xylylenediamine, 1,3-bis(aminomethyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diaza-octamethylenediamine), tetraethylenepentamine, pentamethylenehexamine, dipropylenetriamine, tripropylenetetramine, tetrapropylenepentamine, 4,7-diaza-decamethylene-1,10-diamine, bis(4-aminocyclohexyl)methane, bis(4-amino-3-methylcyclohexyl)methane, 3(4),8(9)bis(aminomethyl)tricyclo[5.2.1.0<sup>2,6</sup>]decane, and mixtures thereof.

19. (New) The two-component epoxy resin composition as claimed in claim 4, wherein the polyamine is selected from the group consisting of 1,3-xylylenediamine, 1,3-bis(aminomethyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diazaoctamethylenediamine), tetraethylenepentamine, isophoronediamine, 1,2-diaminocyclohexane, 4,7-diaza-decamethylene-1,10-diamine, and mixtures thereof.